



1756

PATENT #6

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent
appln. of: Michael Guggemos, et al.

Serial No: 10/069,417

Filed: February 25, 2002

For: **METHOD OF FORMING
A CONDUCTIVE PATTERN
ON DIELECTRIC
SUBSTRATES**

Docket No.: 009-02

Commissioner for Patents
Washington, D.C. 20231

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Date of Deposit: July 15, 2002

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Dear Sir:

Please find enclosed the following for filing in the U.S. Patent and Trademark
Office:

- 1) This Transmittal Sheet;
- 2) Information Disclosure Citation (Form PTO 1449) (in duplicate) and cited references;
- 3) Supplement Information Disclosure Statement; and
- 4) Acknowledgement post card to be date-stamped and returned to Paul and Paul.

The Office is hereby authorized to charge any additional fee, or credit any overpayment, to our Deposit Account No. 16-0750, Order No. 0697.

Respectfully submitted

July 15, 2002

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In re patent
appln. of: Michael Guggemos, et al.

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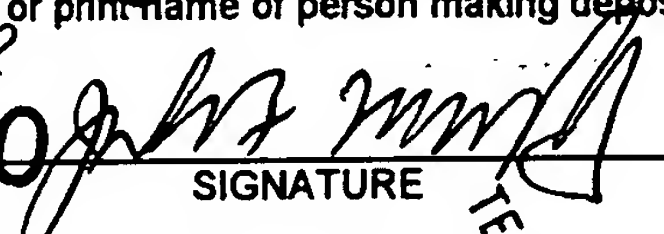
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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

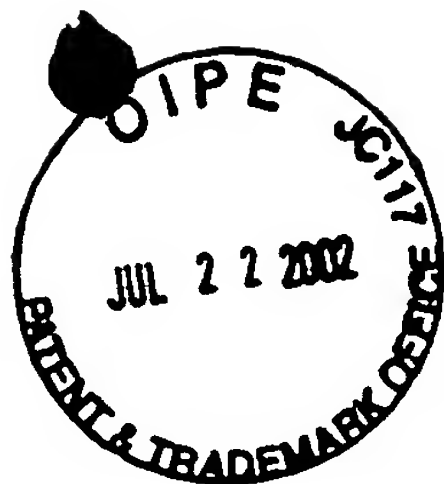
Sir:

In accordance with applicant's duty of disclosure under 35 U.S.C. § 1.56(a) and pursuant to 37 C.F.R. §§ 1.97-1.98, applicant submits herewith patents, publications, or other information of which he is aware which he believes may be material to the examination of this application in respect of which there may be a duty to disclose.

Applicant submits legible copies of the following document listed on the enclosed Patent and Trademark Office - Form 1449 "List of Patents and Publications for Applicant's Supplemental Information Disclosure Statement."

The filing of this Supplemental Information Disclosure Statement shall not be construed to mean that a search has been made, an admission that the information cited is, or is considered to be, material to patentability, or that no other material information, as defined in 37 C.F.R. § 1.56(a), exists. Further, the filing of this supplemental information disclosure statement shall not be construed as an admission against any interest in any manner.

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The Examiner may find the enclosed documents relevant to the invention of the present application.

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U.S. PATENT DOCUMENTS

U.S. Patent 5,114,831 relates to laminated material that can be photopolymerized and contains a tricyclic heteroaromatic compound for use as a photoresist in the production of printed circuit boards.

U.S. Patent 5,294,519 relates to a process for preparing a printed circuit board. The process involves coating a photosensitive electrodeposition coating composition onto a printed-circuit copper clad, laminated base plate to form a photosensitive resist film.

FOREIGN PATENT DOCUMENTS

<u>Serial No.</u>	<u>Country</u>	<u>Date</u>	<u>Inventors</u>
42 22 968 A1	DE	1/20/94	Hoechst AG
WO 97/15173	PCT	4/24/97	Isberg, et al.
WO 98/33951	PCT	8/6/98	Taylor

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The present invention is believed patentable and unobvious over each of these references individually, or taken in any combination, including combination with art previously made of record.

The individual making this statement is the attorney who signs below on the basis of the information supplied by the inventors.

The Examiner may find the enclosed documents relevant to the invention of the present application.

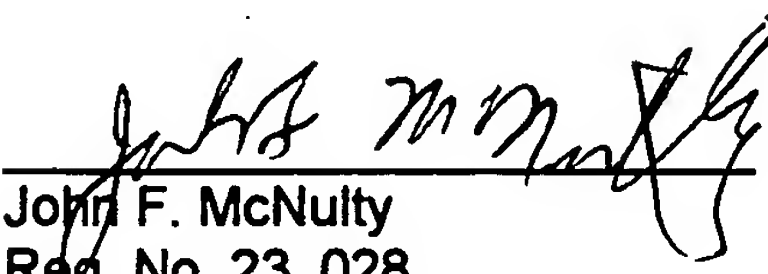
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The Examiner is respectfully requested to review the cited references and to make the cited references of record in the case.

Respectfully submitted,

July 11, 2002

Order No. 0697


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